

<b>Notice of References Cited</b>	Application/Control No. 10/787,476	Applicant(s)/Patent Under Reexamination BIETSCH ET AL	
	Examiner Emmanuel S. Luk	Art Unit 1722	Page 1 of 1

**U.S. PATENT DOCUMENTS**

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
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	C	US-			
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**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Bietsch et al, Conformal contact and pattern stability of stamps used for soft lithography, 10/1/2000, Journal of Applied Physics, Volume 88, number 7, pages 4310-4318.
	V	Michel et al, Printing meets lithography: Soft approaches to high-resolution patterning, IBM Journal of research and development, Advanced Semiconductor Lithography, Volume 45, Number 5, 2001.
	W	
	X	

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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